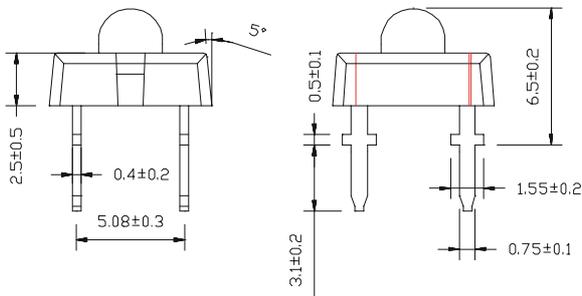
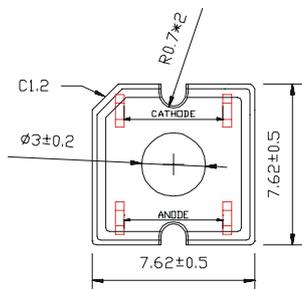


## Device Selection Guide

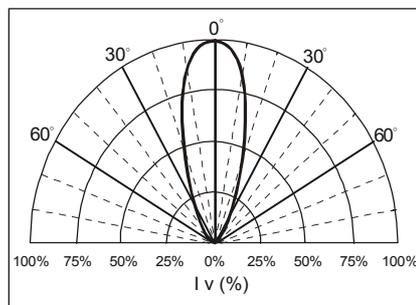
Part Number EOZ-	Total Flux $\Phi_v(\text{mIm}) @ I_F = 50\text{mA}$		Luminous Intensity $I_v(\text{mcd}) / \Phi_v(\text{mIm})$ $@ I_F = 50\text{mA}$	Viewing Angle $2\theta_{1/2}$	Dominant Wavelength $\lambda_D(\text{nm}) @ I_F = 50\text{mA}$	Forward Voltage $V_F(\text{V}) @ I_F = 50\text{mA}$		$I_R(\mu\text{A})$ $@ V_R = 5\text{V}$
	Min.	Typ.	Typ.	Typ.	Typ.	Typ.	Max.	Max.
ZBFHCD0-EG	2750	4500	1.90	40°	525	4.0	4.6	10

BIN #	E	F	G		
Total Flux (mIm) $@ I_F = 50\text{mA}$	2750-3850	3850-5400	5400-7600		

## Package Dimensions



## Beam Pattern



**Note:**

- All dimensions are in millimeter.
- Unspecified tolerance :  $\pm 0.20\text{mm}$ .
- Protruded resin under bottom surface of epoxy is 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to be changed without notice.

## Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Symbol	Maximum Value	USER---APPROVED
Average Forward Current	$I_F$	50mA	
Peak Forward Current <sup>[a]</sup>	$I_{\text{peak}}$	80mA	
Reverse Voltage	$V_R$	5V	
Power Dissipation	$P_D$	230mW	
Operating Temperature Range	$T_{\text{OPR}}$	-40°C ~ + 85°C	
Storage Temperature Range	$T_{\text{STO}}$	-40°C ~ + 100°C	
Lead Soldering Temperature	$T_{\text{SOL}}$	260°C / 5 seconds	

Notes: [a] Duty Ratio = 1/10, Pulse Width = 0.1ms.

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